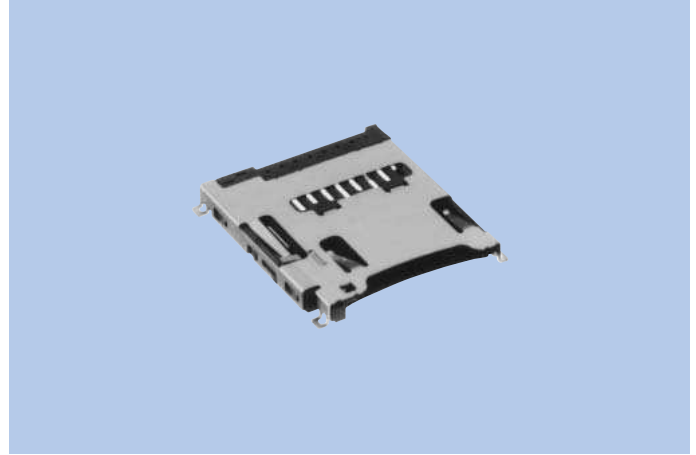


microSD Memory Card Connectors

CIM-H52R

FEATURES

1. Push-in Push-out eject mechanism.
Card eject distance 3.8mm
2. Small and tin design
Reverse mount type : H 1.85mm W 14.0mm
Length 16.0mm
3. Prevent card jump out of a connector with brake mechanism.
4. Switch With card detection [Normally open type]
5. Prevent card drop from connector with half lock mechanism.



HOW TO ORDER

H52R-008-21 0 - A G G E
1 2 3 4 5 6 7 8

- 1 Series No. (H52R : Reverse type)
- 2 No. of contacts (008 : 8pins)
- 3 Housing material (21 : LCP resin)
- 4 Housing UL grade (0 : UL94V-0)
- 5 Contact plating (A : Gold)
- 6 Contact plating thickness (G : 0.3µm)
- 7 Contact read style (G : Angle SMT)
- 8 Package (E : Taping)

SPECIFICATIONS

ELECTRICAL CHARACTERISTICS

Rated Voltage	AC 50V (rms)
Rated Current	0.5A
Withstanding Voltage	500V AC (rms) 1minute
Insulation Resistance	1000MΩ min. (Initial value)
Contact Resistance	100mΩ max. (Initial value)

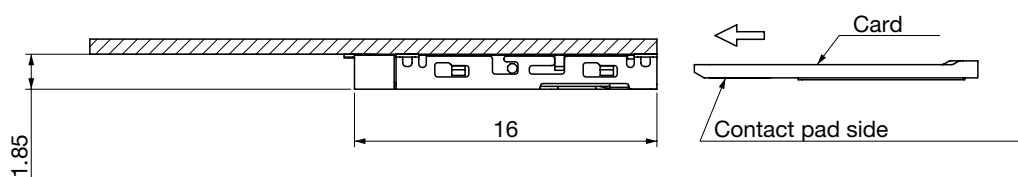
MECHANICAL CHARACTERISTICS

Life (Matching Cycle)	10,000times
Card Insertion Force	2.0N~6.0N
Eject Force	2.0N~6.0N
Using Temperature Range	-25~+85°C

MATERIAL & FINISH

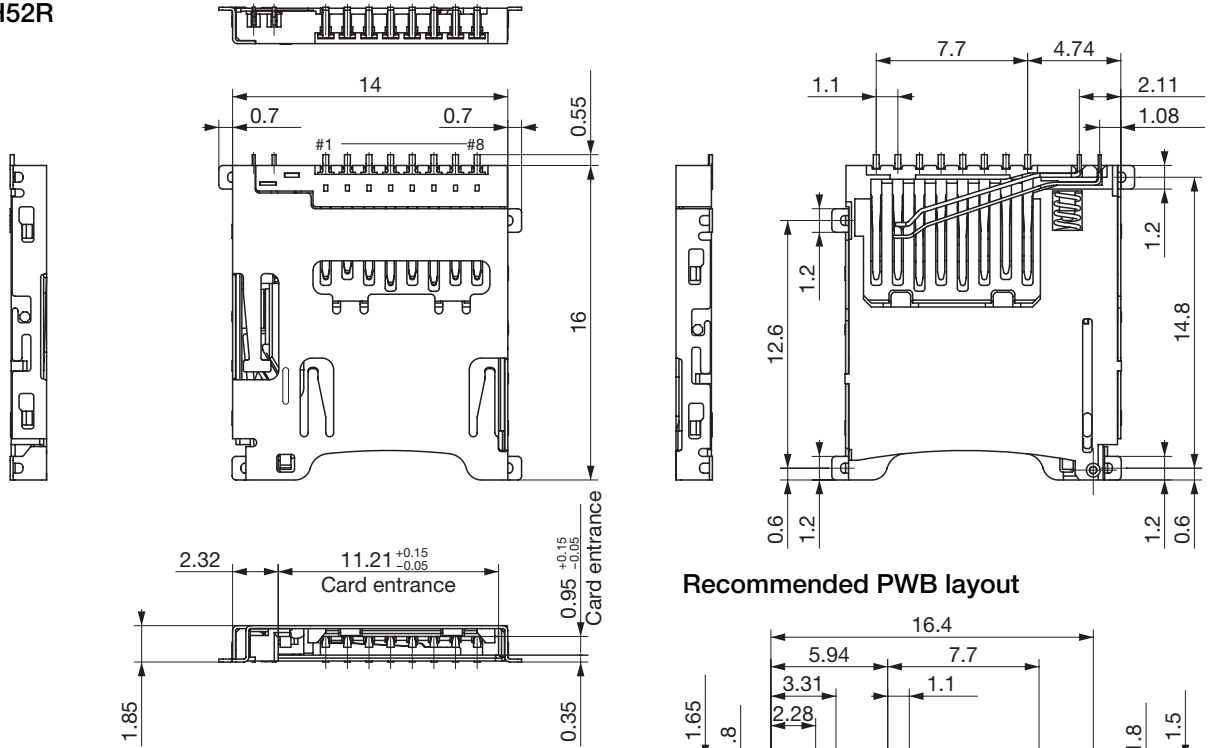
Component Parts	Material	Finish
Housing	LCP resin	Black
Contact	Copper Alloy	Gold plating
CD Switch Vdd	Copper Alloy	Gold plating
CD Switch Vss	Copper Alloy	Gold plating
Plate	Copper Alloy	-
Slider	PA9T resin	Black
Half Lock	SUS	-
Coil Spring	SUS	-
Lock Pin	SUS	-

Board installation condition

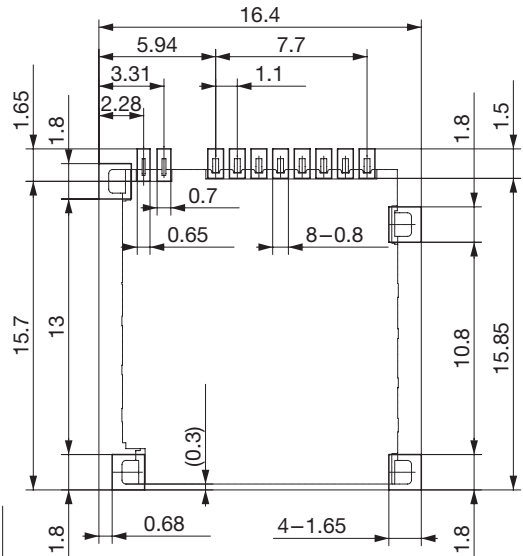


DIMENSIONS

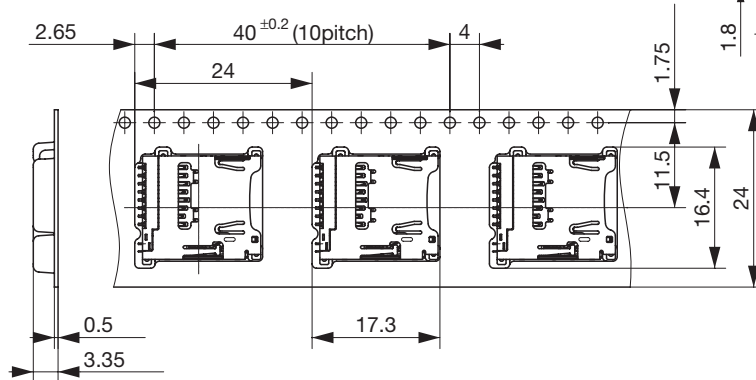
CIM-H52R



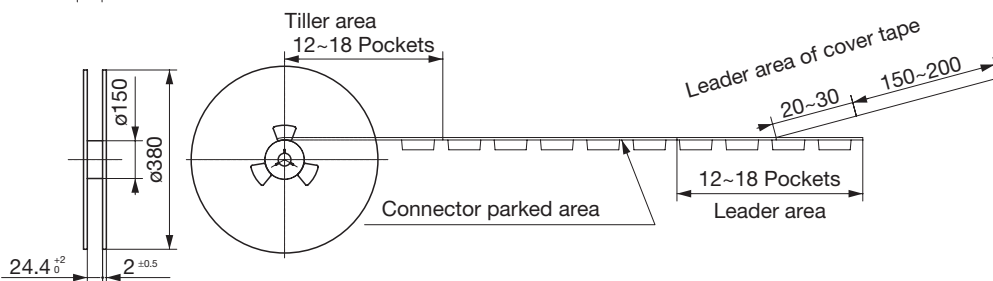
Recommended PWB layout



Packing specification



Recommended PWB layout (NTS) ± 0.05



• Any products mentioned in this catalog are subject to any modification in their appearance and others for improvements without prior notification.
 • The details listed here are not a guarantee of the individual products at the time of ordering. When using the products, you will be asked to check their specifications.